

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5606679

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
VAL G. COOK	05/24/2019
SATYAKI KONERU	05/15/2019
KE YIN	05/09/2019
DINAKAR C. MUNAGALA	05/09/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	THINCI, INC.
<b>Street Address:</b>	4659 GOLDEN FOOTHILL PARKWAY
<b>Internal Address:</b>	SUITE 201
<b>City:</b>	EL DORADO HILLS
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95762
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16416179
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	4088889830
<b>Email:</b>	short.br@gmail.com
<b>Correspondent Name:</b>	LAW OFFICE OF BRIAN SHORT
<b>Address Line 1:</b>	PO BOX 641867
<b>Address Line 4:</b>	SAN JOSE, CALIFORNIA 95164-1867
<b>ATTORNEY DOCKET NUMBER:</b>	THINCI-P001B-CON
<b>NAME OF SUBMITTER:</b>	BRIAN SHORT
<b>SIGNATURE:</b>	/Brian Short/
<b>DATE SIGNED:</b>	07/08/2019
<b>Total Attachments: 4</b>	
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## ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set forth in the patent application entitled:

### NODE TOPOLOGY EMPLOYING RECIRCULATING RING COMMAND AND DATA BUFFERS FOR EXECUTING THREAD SCHEDULING

(Atty. Docket No.: ThinCI-P001B-CON) for which I (we) have executed an application for a United States Letters Patent.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/We the undersigned inventor(s) hereby:

- 1) Sell(s), assign(s) and transfer(s) to ThinCI, Inc. a Delaware corporation having a place of business at 4659 Golden Foothill Parkway, Suite 201, El Dorado Hills, CA 95762 (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.
- 6) Declare:

That the instant Patent Application is based upon an invention conceived and reduced to practice in whole during the course of my responsibilities at ThinCI, Inc. (TI).

- a) No more than incidental use of resources other than TI resources was used in the conception or reduction to practice of the invention.

- b) No part of the conception or reduction to practice of the invention was based upon work performed for any other entity (including a Corporation or University).
- c) Assigning this invention to TI is not in conflict with any previously existing contractual obligation with any other entity (including a Corporation or University).
- d) No information defined as confidential or proprietary by any non- TI entity (including a Corporation or University) was used in the conception or reduction to practice of the invention.

Signed on the date(s) indicated beside my (our) signature(s).

1. Inventor Signature:  Date: 24 May, 2019  
Val G. Cook

.....

2. Inventor Signature: \_\_\_\_\_ Date: \_\_\_\_\_, 2019  
Satyaki Koneru

.....

3. Inventor Signature: \_\_\_\_\_ Date: \_\_\_\_\_, 2019  
Ke Yin

.....

4. Inventor Signature: \_\_\_\_\_ Date: \_\_\_\_\_, 2019  
Dinakar C. Munagala

.....

- c) Assigning this invention to TI is not in conflict with any previously existing contractual obligation with any other entity (including a Corporation or University).
- d) No information defined as confidential or proprietary by any non- TI entity (including a Corporation or University) was used in the conception or reduction to practice of the invention.

Signed on the date(s) indicated beside my (our) signature(s).

1. Inventor Signature: \_\_\_\_\_ Date: \_\_\_\_\_, 2019  
Val G. Cook

2. Inventor Signature: \_\_\_\_\_ Date: May 15th, 2019  
  
Satyaki Koneru

3. Inventor Signature: \_\_\_\_\_ Date: \_\_\_\_\_, 2019  
Ke Yin

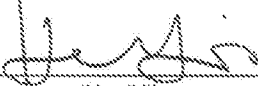
4. Inventor Signature: \_\_\_\_\_ Date: \_\_\_\_\_, 2019  
Dinakar C. Munagala

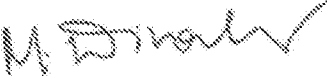
- c) Assigning this invention to TI is not in conflict with any previously existing contractual obligation with any other entity (including a Corporation or University).
- d) No information defined as confidential or proprietary by any non- TI entity (including a Corporation or University) was used in the conception or reduction to practice of the invention.

Signed on the date(s) indicated beside my (our) signature(s).

1. Inventor Signature: \_\_\_\_\_ Date: \_\_\_\_\_, 2019  
Val G. Cook

2. Inventor Signature: \_\_\_\_\_ Date: \_\_\_\_\_, 2019  
Satyaki Koneru

3. Inventor Signature:  \_\_\_\_\_ Date: May 9th, 2019  
Ke Yin

4. Inventor Signature:  \_\_\_\_\_ Date: May 09, 2019  
Dinakar C. Munagala